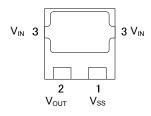
■PIN CONFIGURATION



(BOTTOM VIEW)

■PIN ASSIGNMENT

PIN NUMBER	PIN NAME	FUNCTION	
USP-3	FIN NAIVIL		
3	Vin	Supply Voltage	
1	Vss	Ground	
2	Vout	Output	

■PRODUCT CLASSIFICATION

Ordering Information

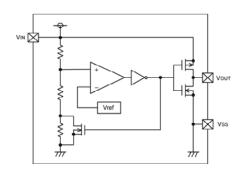
XC61G 1234567-8 (*1)

DESIGNATOR	ITEM	SYMBOL	DESCRIPTION
1)	Output Configuration	С	CMOS output
	① Output Configuration	N	N-ch open drain output
23	Dotoct Voltago	08 ~ 60	e.g. 0.8V → ②0, ③8
23	②③ Detect Voltage		e.g. 1.5V → ②1, ③5
4	Output Delay	0	No delay
(5)	Detect Accuracy	2	Within ± 2%
67-8	Packages (Order Unit)	HR	USP-3 (3,000/Reel)
		HR-G	USP-3 (3,000/Reel)

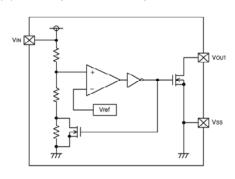
^(*1) The "-G" suffix indicates that the products are Halogen and Antimony free as well as being fully RoHS compliant.

■BLOCK DIAGRAMS

(1) CMOS Output



(2) N-ch Open Drain Output



■ ABSOLUTE MAXIMUM RATINGS

Ta = 25°C

PARAMETER		SYMBOL	RATINGS	UNITS		
Input Voltage		*1	Vin	V _{SS} -0.3 ~ 9.0	٧	
input voita	ige	*2	VIIN	V _{SS} -0.3 ~ 12.0	v	
Output Cur	Output Current		lout	50	mA	
Output Cur	rent	*2	1001	50	IIIA	
	СМО	S		Vss -0.3 ~ Vin +0.3		
Output Voltage	Output Voltage N-ch Open Drai		*1 Vout	Vss -0.3 ~ 9.0	V	
	N-ch Open Drai	in Output *2		Vss -0.3 ~ 12.0		
Power Dissipation	USP-3		Pd	120	mW	
Operating Ambient Temperature		Topr	-40 ~ +85	°C		
Storage Temperature Range		Tstg	-40~+125	°C		

■ELECTRICAL CHARACTERISTICS

 $V_{DF(T)} = 0.8 \text{ to } 6.0V \pm 2\%$

PARAM	METER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUITS
Detect Voltage		VDF	V _{DF(T)} =0.8V~1.5V ^{*1}		V_{DF}	V_{DF}	V_{DF}	V	1
Beteet	voltage	VDI	$V_{DF(T)}=1.6V\sim6.0V^{*2}$		x 0.98		x 1.02	V	
Hysteres	Hysteresis Range					V_{DF}	V_{DF}	· · · · · · · · · · · · · · · · · · ·	1
,		VHYS			x 0.02	x 0.05	x 0.08	-	-
			V _{IN} = 1.5V		-	0.7	2.3		
			V _{IN} = 2.0V		-	8.0	2.7		
Supply	Current	Iss	$V_{IN} = 3.0V$		-	0.9	3.0	μΑ	2
			$V_{IN} = 4.0V$		-	1.0	3.2		
			$V_{IN} = 5.0V$	1	-	1.1	3.6		
Operating	g Voltage	V _{IN}	$V_{DF(T)} = 0.8V tc$	1.5V	0.7	-	6.0	V	1
Орстанту	g voltage	VIN	$V_{DF(T)} = 1.6V tc$	6.0V	0.7	-	10.0	V	•
Output	Output Current (Low Voltage)		N-ch, V _{DS} = 0.5V -	V _{IN} =0.7V	0.10	0.80	-	mA	3
-				V_{IN} =1.0 V	0.85	2.70	-		
(LOW V			CMOS, P-ch, V _{DS} =2.1V	V _{IN} =6.0V	-	-7.5	-1.5		4
			-	V _{IN} =1.0V	1.0	2.2	ı		
				V _{IN} =2.0V	3.0	7.7	ı		,
Output	Current	l _{out}	N-ch, $V_{DS} = 0.5V$	V _{IN} =3.0V	5. 0	10.1	ı		3
	(Standard Voltage)		-	$V_{IN} = 4.0V$	6.0	11.5	-	-	
,				V _{IN} =5.0V	7.0	13.0	-		
			CMOS, P-ch, V _{DS} =2.1V	V _{IN} =8.0V	-	-10.0	-2.0		4
	CMOS								
Leakage	Output		$V_{IN}=V_{DF}x0.9, V_{OUT}=0V$ $V_{IN}=6.0V, V_{OUT}=6.0V^{*1}$		10	-			
Current	(Pch)	I _{LEAK}				nA	3		
Current	N-ch Open				_	10	100		
	Drain		V _{IN} =10.0V, V _{OUT} =10.0V ^{*2}			10	100		
-	erature	ΔV_{DF}	-40°C ≦ Topr ≦ 85°C		-	±100	_	ppm/	1
	teristics	(∆Topr·V _{DF})				-		°C	
	Time	t _{DLY}	V _{DR} →Vout inve	ersion	-	0.03	0.2	ms	5
(VDR → VOUT inversion)			VER VEET IIIVOIOIII						

NOTE:

 $V_{DF(T)}$: Nominal detect voltage Release Voltage: $V_{DR} = V_{DF} + V_{HYS}$

^{*1 :} Low Voltage ($V_{DF(T)}$ =0.8 $V \sim$ 1.5V)

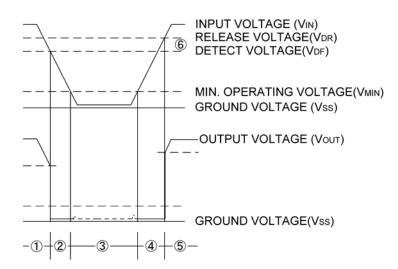
^{*2 :} Standard Voltage ($V_{DF(T)}$ =1.6 V \sim 6.0V)

■OPERATIONAL EXPLANATION

CMOS output

- (VDF), output voltage (VOUT) will be equal to VIN. (A condition of high impedance exists with N-ch open drain output configurations.)
- ② When input voltage (VIN) falls below detect voltage (VDF), output voltage (VOUT) will be equal to the ground voltage (VSS) level.
- ③ When input voltage (Vin) falls to a level below that of the minimum operating voltage (VMIN), output will become unstable. (As for the N-ch open drain product of XC61CN, the pull-up voltage goes out at the output voltage.)
- When input voltage (VIN) rises above the ground voltage (VSS) level, output will be unstable at levels below the minimum operating voltage (VMIN). Between the VMIN and detect release voltage (VDR) levels, the ground voltage (VSS) level will be maintained.
- (VDR), output voltage (VOT) will be equal to VIN. (A condition of high impedance exists with N-ch open drain output configurations.)
- 6 The difference between VDR and VDF represents the hysteresis range.

Timing Chart



■NOTES ON USE

- 1. Please use this IC within the stated absolute maximum ratings. For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.
- 2. When a resistor is connected between the V_{IN} pin and the power supply with CMOS output configurations, oscillation may occur as a result of voltage drops at R_{IN} if load current (I_{OUT}) exists. (refer to the Oscillation Description (1) below)
- 3. When a resistor is connected between the V_{IN} pin and the power supply with CMOS output configurations, irrespective of N-ch open-drain output configurations, oscillation may occur as a result of through current at the time of voltage release even If load current (IouT) does not exist. (refer to the Oscillation Description (2) below)
- 4. Please use N-ch open drain output configuration, when a resistor R_{IN} is connected between the V_{IN} pin and power source. In such cases, please ensure that R_{IN} is less than $10k\Omega$ and that C is more than $0.1\,\mu$ F, please test with the actual device. (refer to the Oscillation Description (1) below)
- 5. With a resistor R_{IN} connected between the V_{IN} pin and the power supply, the V_{IN} pin voltage will be getting lower than the power supply voltage as a result of the IC's supply current flowing through the V_{IN} pin.
- 6. In order to stabilize the IC's operations, please ensure that V_{IN} pin input frequency's rise and fall times are more than 2 μ s/ V.
- 7. Torex places an importance on improving our products and its reliability.

 However, by any possibility, we would request user fail-safe design and post-aging treatment on system or equipment.

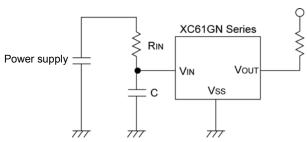


Figure 1: Circuit using an input resistor

Oscillation Description

(1) Load current oscillation with the CMOS output configuration

When the voltage applied at power supply, release operations commence and the detector's output voltage increases. Load current (IOUT) will flow at RL. Because a voltage drop (RIN x IOUT) is produced at the RIN resistor, located between the power supply and the VIN pin, the load current will flow via the IC's VIN pin. The voltage drop will also lead to a fall in the voltage level at the VIN pin. When the VIN pin voltage level falls below the detect voltage level, detect operations will commence. Following detect operations, load current flow will cease and since voltage drop at RIN will disappear, the voltage level at the VIN pin will rise and release operations will begin over again.

Oscillation may occur with this "release - detect - release" repetition.

Further, this condition will also appear via means of a similar mechanism during detect operations.

(2) Oscillation as a result of through current

Since the XC61G series are CMOS IC s, through current will flow when the IC's internal circuit switching operates (during release and detect operations). Consequently, oscillation is liable to occur as a result of drops in voltage at the through current's resistor (RIN) during release voltage operations. (refer to Figure 3)

Since hysteresis exists during detect operations, oscillation is unlikely to occur.

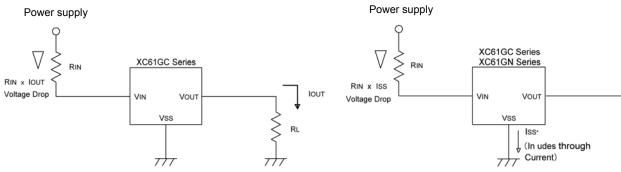
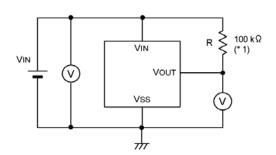


Figure 2: Oscillation in relation to output current

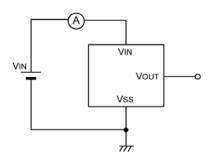
Figure 3: Oscillation in relation to through current

■TEST CIRCUITS

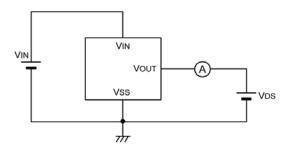
Circuit 1



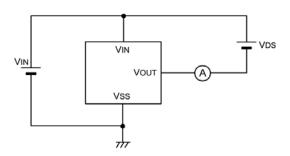
Circuit 2



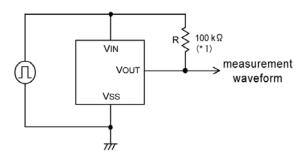
Circuit 3



Circuit 4



Circuit 5

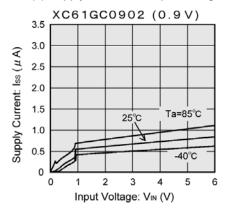


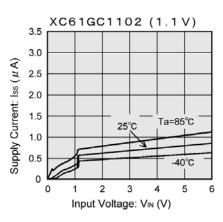
* 1: The resistor is not necessary with CMOS output products.

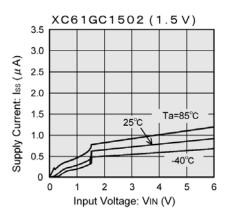
■TYPICAL PERFORMANCE CHARACTERISTICS

Low Voltage

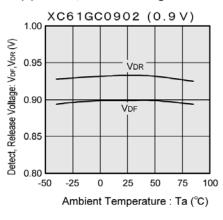
(1) Supply Current vs. Input Voltage

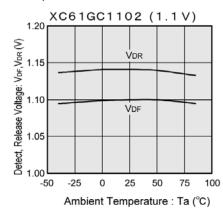


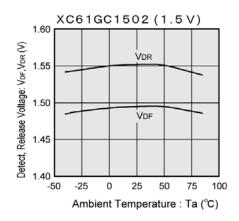




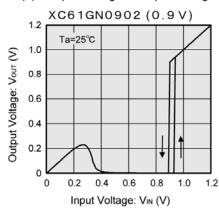
(2) Detect, Release Voltage vs. Ambient Temperature

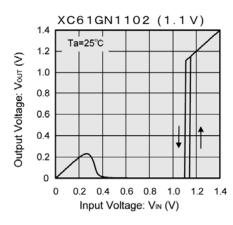


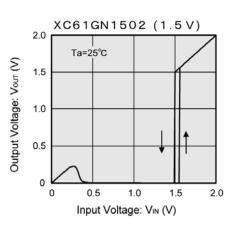




(3) Output Voltage vs. Input Voltage



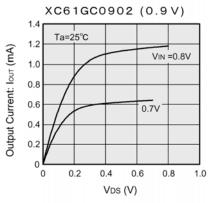


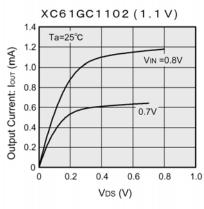


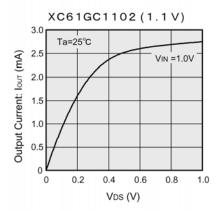
Note: Unless otherwise stated, the N-ch open drain pull-up resistance value is $100k\,\Omega$.

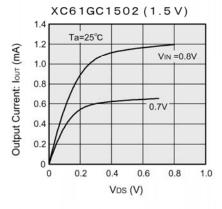
■Low Voltage (Continued)

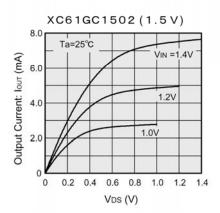


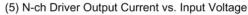


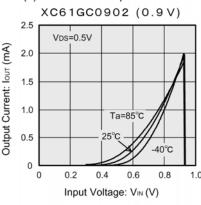


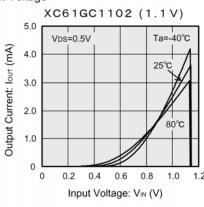


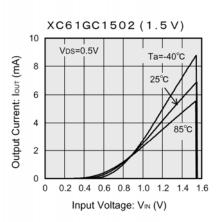




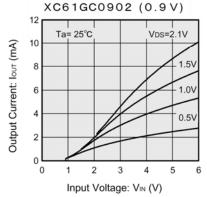


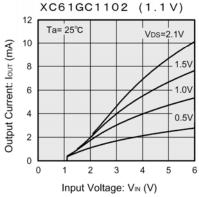


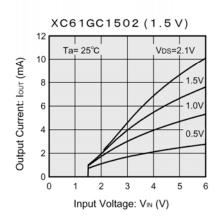




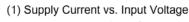
(6) P-ch Driver Output Current vs. Input Voltage

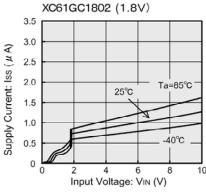


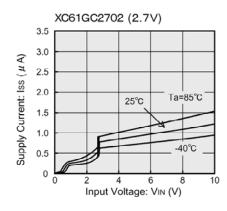


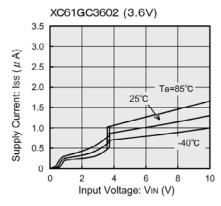


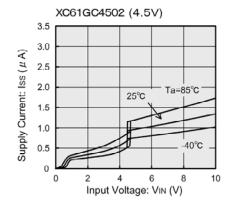
Standard Voltage



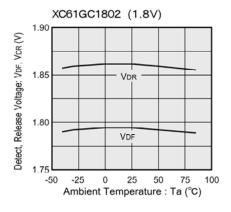


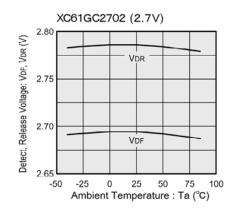


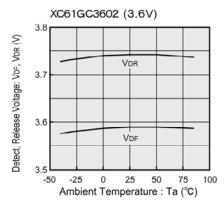


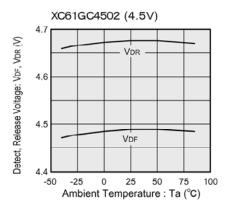


(2) Detect, Release Voltage vs. Ambient Temperature



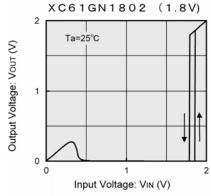


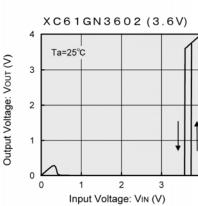


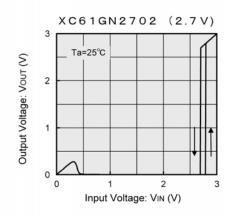


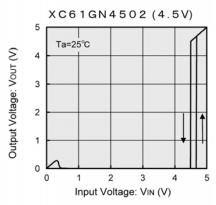
Standard Voltage (Continued)

(3) Output Voltage vs. Input Voltage



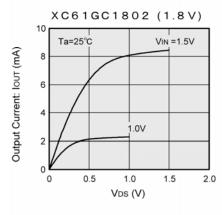


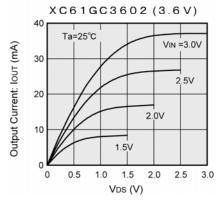


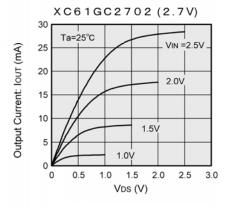


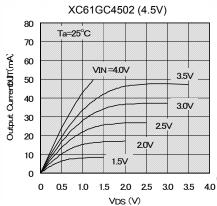
Note: Unless otherwise stated, the N-ch open drain pull-up resistance value is $100k\,\Omega$.





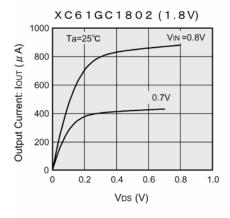


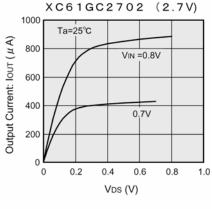


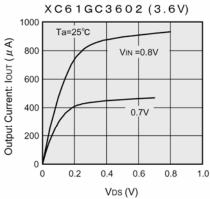


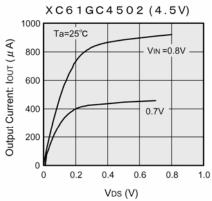
Standard Voltage (Continued)

(4) N-ch Driver Output Current vs. VDS

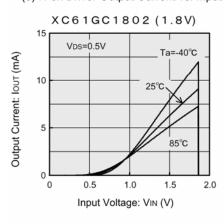


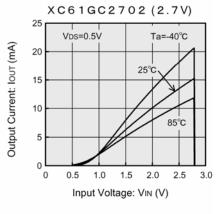


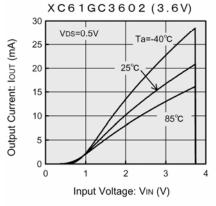


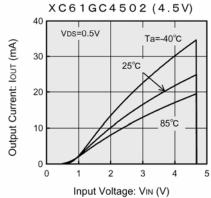


(5) N-ch Driver Output Current vs. Input Voltage



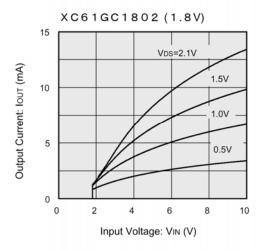


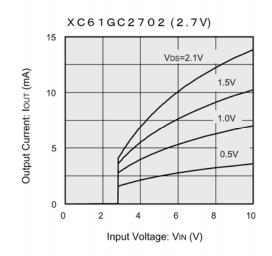


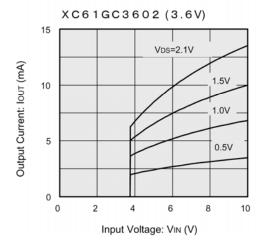


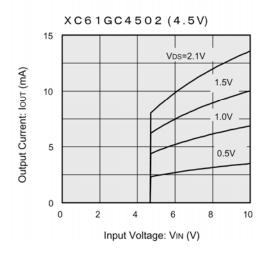
Standard Voltage (Continued)

(6) P-ch Driver Output Current vs. Input Voltage





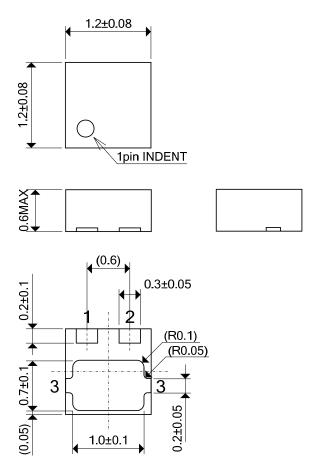




■ PACKAGING INFORMATION

●USP-3

(unit: mm)

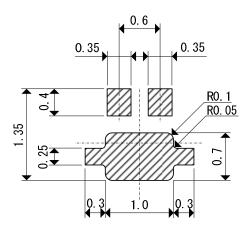


XC61G Series

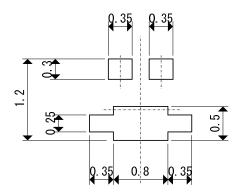
■ PACKAGING INFORMATION (Continued)

●USP-3

Reference Pattern Layout Dimension

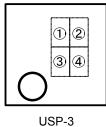


Reference metal mask design



■MARKING RULE

●USP-3



USP-3 (TOP VIEW)

① represents integer of output voltage and detect voltage

CMOS Output (XC61GC series)

N-ch Open Drain Output (XC61GN series)

MARK	VOLTAGE (V)
Α	0.X
В	1.X
С	2.X
D	3.X
E	4.X
F	5.X
Н	6.X

MARK	VOLTAGE (V)
K	0.X
L	1.X
M	2.X
N	3.X
Р	4.X
R	5.X
S	6.X

② represents decimal number of detect voltage

Ex:

MARK	VOLTAGE (V)	PRODUCT SERIES
3	X.3	XC61G**3
0	X.0	XC61G**0

3 represents delay time

MARK	Delay Time	PRODUCT SERIES
3	No	XC61G***0

Prepresents production lot number 0 to 9,A to Z reverse character 0 to 9, A to Z repeated (G, I, J, O, Q, W excluded)

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        XC61GC2502HR-G

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